

EVLYS LTD. - POWER SEMICONDUCTORS DEVICES -
Wholesale and Retail.

Phase Control Disc Thyristor Type DT32-250-36

High power cycling capability / Low on-state and switching losses
 Designed for traction and industrial applications

Mean on-state current	I _{TAV}	250 A		
Repetitive peak off-state voltage	V _{DRM}	3000 ÷ 3600 V		
Repetitive peak reverse voltage	V _{RRM}			
Turn-off time	t _q	250, 320, 400, 500 µs		
V _{DRM} , V _{RRM} , V	3000	3200	3400	3600
Voltage code	30	32	34	36
T _j , °C		-60 ÷ 125		

MAXIMUM ALLOWABLE RATINGS

Symbols and parameters		Units	Values	Test conditions	
ON-STATE					
I _{TAV}	Mean on-state current	A	250 335	T _c =100 °C, Double side cooled T _c =85 °C, Double side cooled 180° half-sine wave; 50 Hz	
I _{TRMS}	RMS on-state current	A	392	T _c =100 °C, Double side cooled 180° half-sine wave; 50 Hz	
I _{TSM}	Surge on-state current	kA	6.5 7.5	T _j =T _j ^{max} T _j =25 °C	180° half-sine wave; 50 Hz (t _p =10 ms); single pulse; V _D =V _R =0 V; Gate pulse: I _G =2 A; t _{GP} =50 µs; di _G /dt≥1 A/µs
			7.0 8.1	T _j =T _j ^{max} T _j =25 °C	180° half-sine wave; 60 Hz (t _p =8.3 ms); single pulse; V _D =V _R =0 V; Gate pulse: I _G =2 A; t _{GP} =50 µs; di _G /dt≥1 A/µs
I ² t	Safety factor	A ² s·10 ³	210 280	T _j =T _j ^{max} T _j =25 °C	180° half-sine wave; 50 Hz (t _p =10 ms); single pulse; V _D =V _R =0 V; Gate pulse: I _G =2 A; t _{GP} =50 µs; di _G /dt≥1 A/µs
			200 270	T _j =T _j ^{max} T _j =25 °C	180° half-sine wave; 60 Hz (t _p =8.3 ms); single pulse; V _D =V _R =0 V; Gate pulse: I _G =2 A; t _{GP} =50 µs; di _G /dt≥1 A/µs
BLOCKING					
V _{DRM} , V _{RRM}	Repetitive peak off-state and Repetitive peak reverse voltages	V	3000÷3600	T _{j min} < T _j <T _{j max} ; 180° half-sine wave; 50 Hz; Gate open	
V _{DSM} , V _{RSM}	Non-repetitive peak off-state and Non-repetitive peak reverse voltages	V	3100÷3700	T _{j min} < T _j <T _{j max} ; 180° half-sine wave; 50 Hz;single pulse; Gate open	
V _D , V _R	Direct off-state and Direct reverse voltages	V	0.75·V _{DRM} 0.75·V _{RRM}	T _j =T _j ^{max} ; Gate open	

TRIGGERING				
I _{FGM}	Peak forward gate current	A	6	T _j =T _{j max}
V _{RGM}	Peak reverse gate voltage	V	5	
P _G	Gate power dissipation	W	3	T _j =T _{j max} for DC gate current
SWITCHING				
(di _T /dt) _{crit}	Critical rate of rise of on-state current non-repetitive (f=1 Hz)	A/μs	320	T _j =T _{j max} ; V _D =0.67·V _{DRM} ; I _{TM} =2 I _{TAV} ; Gate pulse: I _G =2 A; t _{GP} =50 μs; di _G /dt≥2 A/μs
THERMAL				
T _{stg}	Storage temperature	°C	-60÷50	
T _j	Operating junction temperature	°C	-60÷125	
MECHANICAL				
F	Mounting force	kN	9.0÷11.0	
a	Acceleration	m/s ²	50 100	Device unclamped Device clamped
CHARACTERISTICS				
Symbols and parameters		Units	Values	Conditions
ON-STATE				
V _{TM}	Peak on-state voltage, max	V	2.50	T _j =25 °C; I _{TM} =785 A
V _{T(TO)}	On-state threshold voltage, max	V	1.20	T _j =T _{j max} ;
r _T	On-state slope resistance, max	mΩ	2.100	0.5 π I _{TAV} < I _T < 1.5 π I _{TAV}
I _L	Latching current, max	mA	700	T _j =25 °C; V _D =12 V; Gate pulse: I _G =2 A; t _{GP} =50 μs; di _G /dt≥1 A/μs
I _H	Holding current, max	mA	300	T _j =25 °C; V _D =12 V; Gate open
BLOCKING				
I _{DRM} , I _{RRM}	Repetitive peak off-state and Repetitive peak reverse currents, max	mA	70	T _j =T _{j max} ; V _D =V _{DRM} ; V _R =V _{RRM}
(dv _D /dt) _{crit}	Critical rate of rise of off-state voltage ¹⁾ , min	V/μs	200, 320, 500, 1000	T _j =T _{j max} ; V _D =0.67·V _{DRM} ; Gate open
TRIGGERING				
V _{GT}	Gate trigger direct voltage, max	V	5.00 3.00 2.00	T _j =T _{j min} T _j =25 °C T _j =T _{j max}
I _{GT}	Gate trigger direct current, max	mA	500 300 200	T _j =T _{j min} T _j =25 °C T _j =T _{j max}
V _{GD}	Gate non-trigger direct voltage, min	V	0.25	T _j =T _{j max} ;
I _{GD}	Gate non-trigger direct current, min	mA	10.00	V _D =0.67·V _{DRM} ; Direct gate current
SWITCHING				
t _{gd}	Delay time	μs	3.00	T _j =25 °C; V _D =0.4·V _{DRM} ; I _{TM} =I _{TAV} ; Gate pulse: I _G =2 A; t _{GP} =50 μs; di _G /dt≥2 A/μs
t _q	Turn-off time ²⁾ , max	μs	250, 320, 400, 500	dv _D /dt=50 V/μs; T _j =T _{j max} ; I _{TM} = I _{TAV} ; di _R /dt=-10 A/μs; V _R =100V; V _D =0.67·V _{DRM}

THERMAL

R_{thjc}	Thermal resistance, junction to case, max	$^{\circ}\text{C}/\text{W}$	0.040	Direct current	Double side cooled	
R_{thjc-A}			0.088		Anode side cooled	
R_{thjc-K}			0.072		Cathode side cooled	
R_{thck}	Thermal resistance, case to heatsink, max	$^{\circ}\text{C}/\text{W}$	0.008	Direct current		

MECHANICAL

W	Weight, typ	g	180		
D_s	Surface creepage distance	mm (inch)	19.44 (0.765)		
D_a	Air strike distance	mm (inch)	12.10 (0.476)		

PART NUMBERING GUIDE

DT 32 250 36 7 2
 1 2 3 4 5 6

1. DT - Phase Control Disc Thyristor
2. Element Diameter
3. Mean on-state current, A
4. Voltage code
5. Critical rate of rise of on-state current non-repetitive, V/ μs
6. Turn-off time ($\text{dv}_D/\text{dt}=50 \text{ V}/\mu\text{s}$)

NOTES

- 1) Critical rate of rise of on-state current non-repetitive

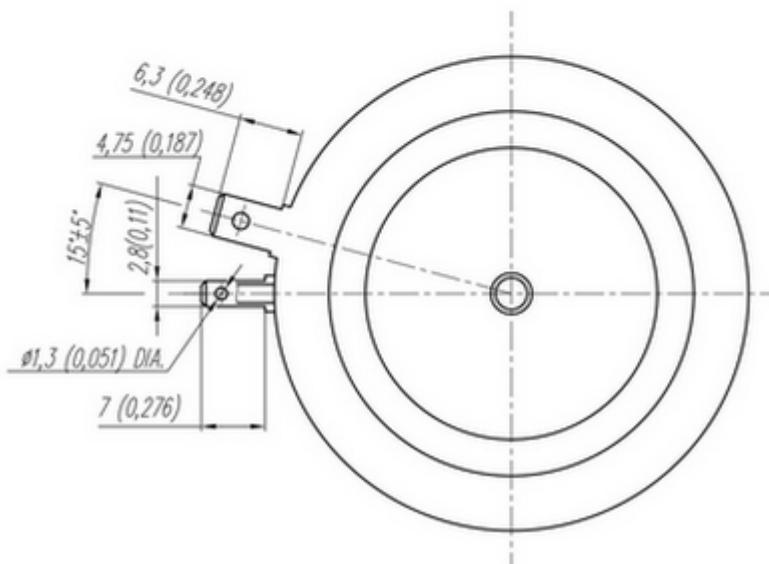
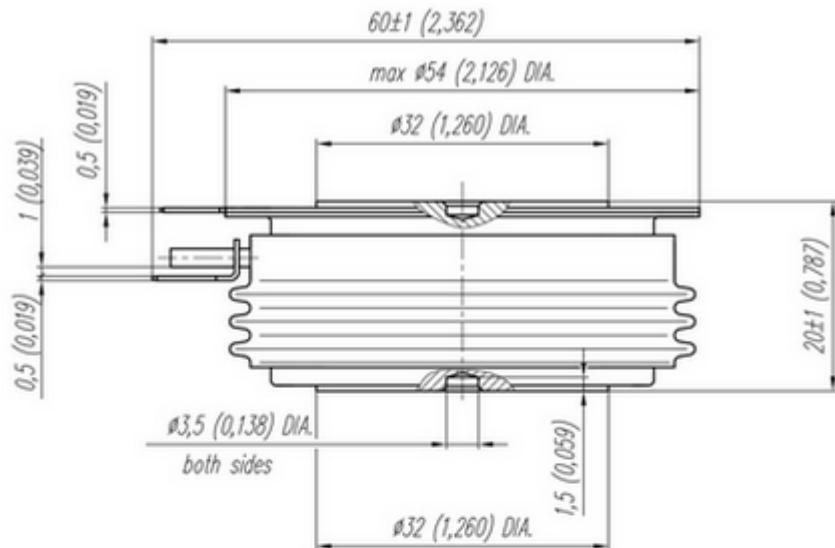
Symbol of Group $(\text{dv}_D/\text{dt})_{\text{crit}}, \text{V}/\mu\text{s}$	4	5	6	7
	200	320	500	1000

- 2) Turn-off time ($\text{dv}_D/\text{dt}=50 \text{ V}/\mu\text{s}$)

Symbol of Group $t_q, \mu\text{s}$	0	0	0	0
	250	320	400	500

OVERALL DIMENSIONS

Package type: T.B3



All dimensions in millimeters (inches)